



1. Dimensions in millimeters.
2. Material: BeO Ceramic with Copper surfaces.
3. Metalization: Ni/Au plated.
4. Dimensional tolerance +/-0.05mm.
5. Indium die attach- 150°C max process temperature.
6. AuSn die attach- 270°C max process temperature.

Title: Chip on Submount Package

LDX Optronics Inc

Date: